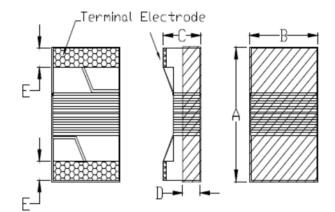


FEATRLRES

- Monolithic inorganic material construction.
- Closed magnetic circuit avoids crosstalk.
- S.M.T. type.
- Suitable for reflow soldering.
- Shapes and dimensions follow E.I.A. spec.
- Available in various sizes.
- Excellent solder ability and heat resistance.
- High reliability.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

CONFIGRLRATIONS & DIMENSIONS (unit in mm)



Size	A	В	С	D	E
SWF1608	1.8max	1.2max	1.2max	0.38ref.	0.35±0.1

ELECTRICAL CHARACTERISTICS

Part Number	Inductance	Tolerance	Test Frequency	Q	Test Frequency	Rated	DCR(Ω)	SRF
rait Hullibel	(uH)	Toterance	(Hz)	min.	(MHz)	Current(mA)	max.	(MHz)min.
SWF1608CF-47NK	0.047±10%	K,M	0.5V/7.96M	10	7.96	1500	0.075	1400
SWF1608CF-R10K	0.10±10%	K,M	0.5V/7.96M	10	7.96	1150	0.13	1400
SWF1608CF-R12K	0.12±10%	K,M	0.5V/7.96M	10	7.96	1100	0.15	1400
SWF1608CF-R15K	0.15±10%	K,M	0.5V/7.96M	10	7.96	1050	0.15	1300
SWF1608CF-R18K	0.18±10%	K,M	0.5V/7.96M	10	7.96	950	0.15	1300
SWF1608CF-R22K	0.22±10%	K,M	0.5V/7.96M	10	7.96	800	0.15	950
SWF1608CF-R24K	0.24±10%	K,M	0.5V/7.96M	10	7.96	800	0.31	620
SWF1608CF-R27K	0.27±10%	K,M	0.5V/7.96M	10	7.96	775	0.20	710
SWF1608CF-R33K	0.33±10%	K,M	0.5V/7.96M	10	7.96	725	0.35	620
SWF1608CF-R39K	0.39±10%	K,M	0.5V/7.96M	10	7.96	620	0.39	600
SWF1608CF-R47K	0.47±10%	K,M	0.5V/7.96M	10	7.96	540	0.43	570
SWF1608CF-R56K	0.56±10%	K,M	0.5V/7.96M	10	7.96	525	0.47	550
SWF1608CF-R68K	0.68±10%	K,M	0.5V/7.96M	10	7.96	460	0.52	470
SWF1608CF-R82K	0.82±10%	K,M	0.5V/7.96M	10	7.96	410	0.69	400
SWF1608CF-1R0K	1.0±10%	K,M	0.5V/7.96M	10	7.96	190	0.81	400

HSIA TECHNOLOGY CO.LTD. TEL:886-2-2999-6691 FAX: 2999-6692 Website:www.hsia.com.tw



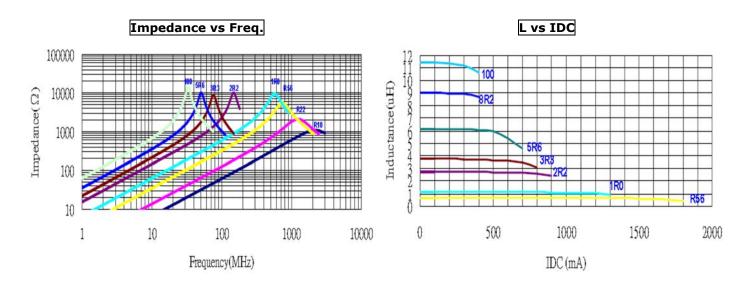
SWF1608CF-1R2K	1.2±10%	K,M	0.5V/7.96M	10	7.96	160	0.87	370
SWF1608CF-1R5K	1.5±10%	K,M	0.5V/7.96M	10	7.96	100	0.96	350
SWF1608CF-1R8K	1.8±10%	K,M	0.5V/7.96M	10	7.96	80	1.10	350
SWF1608CF-2R2K	2.2±10%	K,M	0.5V/7.96M	10	7.96	68	1.20	320
SWF1608CF-3R3K	3.3±10%	K,M	0.5V/7.96M	10	7.96	42	1.50	280
SWF1608CF-3R9K	3.9±10%	K,M	0.5V/7.96M	10	7.96	40	1.50	280
SWF1608CF-4R7K	4.7±10%	K,M	0.5V/7.96M	10	7.96	34	2.10	260
SWF1608CF-5R6K	5.6±10%	K,M	0.5V/7.96M	10	7.96	32	2.60	240
SWF1608CF-6R8K	6.8±10%	K,M	0.5V/7.96M	10	7.96	31	3.10	200
SWF1608CF-8R2K	8.2±10%	K,M	0.5V/7.96M	10	7.96	26	4.40	190
SWF1608CF-100K	10.0±10%	K,M	0.5V/2.52M	10	2.52	25	4.80	180

■ NOTE: $K=\pm 10\%, L=\pm 15\%, M=\pm 20\%$

■ Rated current: based on temperature rise test

■ In compliance with EIA 595

Impedance vs Frequency, DC Bias Characteristics (Typical)



Reliability and Test Condition

Item	Performance	Test Condition				
Operating temperature	-40~+125℃ (Including self - temperature rise)					
Storage temperature	110~+40°ℂ,50~60%RH (Product with taping) 240~+125°ℂ (on board)					
Electrical Performance Test						
Inductance		HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.				
DCR		CH16502,Agilent33420A Micro-Ohm Meter.				



Saturation Current (Isat)	Approximately∆L30%	Saturation DC Current (Isat) will cause L0 to drop △L(%)				
Heat Rated Current (Irms)	Approximately △T40°C	Heat Rated Current (Irms) will cause the coil temperature rise $\triangle T(^{\circ}C)$. 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer				
Reliability Test						
Life Test		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature: 125±2°C (Inductor) Applied current: rated current Duration: 1000±12hrs Measured at room temperature after placing for 24±2 hrs				
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity: 85±2 * R.H, Temperature: 85°C±2°C Duration: 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs				
Moisture Resistance	Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles 1. Baked at50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs, keep at 25°C for 2 hrs then keep at -10°C for 3 hrs 4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.				
Thermal shock		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1: -40±2°C 30±5min Step2: 25±2°C ≤0.5min Step3: 125±2°C 30±5min Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs				
Vibration		Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations).				
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.				
Shock	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Type Peak value (g's) Normal duration (D) (ms) Wave form (vi)ft/sec Velocity change (vi)ft/sec SMD 50 11 Half-sine 11.3 Lead 50 11 Half-sine 11.3				
Solder ability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C,60sec Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C · Flux for lead free: Rosin. 9.5% · Dip time: 4±1sec · Depth: completely cover the termination Depth: completely cover the termination				
Resistance to Soldering Heat		Temperature ramp/immersion and emersion rate heat cycles				
		(solder temp) 10 ±1 25mm/s ±6 mm/s 1				



Appearance: No damage.

Impedance: within±15% of initial value
Inductance: within±10% of initial value
Q: Shall not exceed the specification value and shall not exceed the specification value e

Terminal
Strength

Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles
With the component mounted on a PCB with the device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.

DUT

wide

press tool

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.